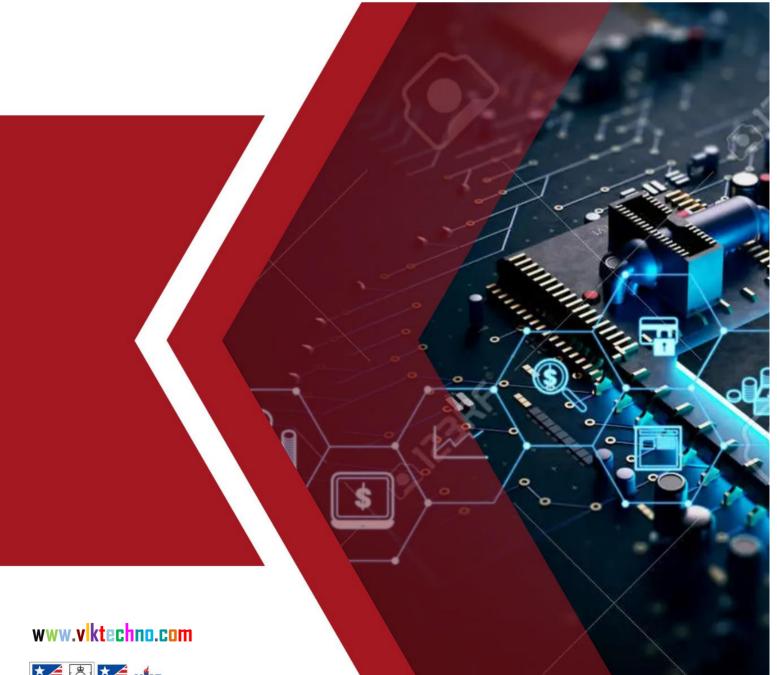


# V.L.K. TECHNO TRADE CO., LTD.

Industrial Solutions

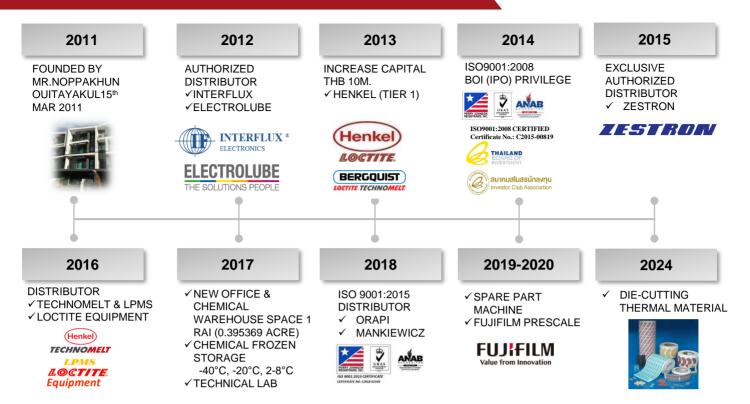








# **COMPANY HISTORY BOARD**



	OUR SERVICE		
	BUFFER STOCK		
	SOURCING		
3	IMPORT DG LICENSE		
	FLEXIBLE & FAST DELIVERY		
5	FREEZER STORAGE 2-8°C / -20°C / -40°C		
	BOI PRIVILEGE		
7	DOWNLOAD CHIPBONDER		
8	DIE-CUTTING : THERMAL MATERIAL		



<b>ELECTROLUBE</b>	https://electrolube.com		
THE SOLUTIONS PEOPLE			
MAKE IT WITH A GLOBAL SOLUTIONS PROVIDER. ELECTROLUBE HAVE BEEN DEVELOPING SOLUTIONS TO ADVANCE ENGINEERING AND ENCHANCE TECHNOLOGICAL PERFORMANCE, SINCE 1941. WITH OUR EXPANSIVE RANGE OF PRODUCTS AND A COMMITMENT TO PUSH THE BOUNDARIES, THERE IS NO END TO THE APPLICATIONS OF ELECTROCHEMICAL SOLUTIONS.			
CONFORMAL COATINGS	MAINTENANCE & SERVICE AIDS		
ELECTRONIC & GENERAL CLEANING	THERMAL MANAGEMENT		
ENCAPSULATION RESINS	CONTACT LUBRICANTS		

Electronic & General	Conformal	Encapsulation	Contact	Maintenance
Purpose Cleaning	Coatings	Resins	Lubricants	& Service Aids

- \* AUTOMOTIVE
- \* MILITARY
- \* AEROSPACE
- \* TRANSPORT
- \* MARINE
- \* TELECOMMUNICATIONS
- \* MEDICAL

- **CONSUMER ELECTRONICS**
- **INDUSTRIAL ELECTRONICS**
- \* TRANSPORT
- **WITILITIES**
- **SERVICE, REPAIR AND MAINTENANCE**
- \* LED



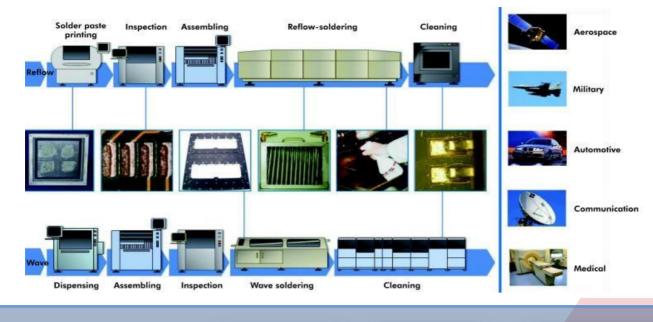


#### Bringing chemistry to electronics for over 42+ years.





### A CLEANING SOLUTION FOR ANY APPLICATION



**ECO-FRIENDLY** SURFACE MOUNT TECHNOLOGY & THROUGH HOLE





**PCB DEFLUXING** CLEANING SOLUTIONS TO REMOVE FLUX RESIDUES



**STENCIL & MISPRINT** REMOVE SOLDER PASTE,



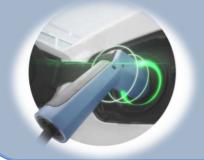
MAINTENANCE REMOVE BAKED-ON FLUX RESIDUE, ADHESIVES AND CONFORMAL COATING

### SEMICONDUCTOR CLEANING **POWER ELECTRONICS,**

ADV.PACKAGING, WAFER



**RISK PREVENTION HIGH VOLTAGE** 



**♦ EXCEPTIONAL COMPATIBILITY** 

- ✤ HIGH WIRE BOND YIELD & RELIABILITY
- IMPROVED PRODUCTIVITY

### **POWER ELECTRONICS CLEANING**

- ✓ POWER MODULES
- ✓ LEADFRAMES
- ✓ POWER LEDs

### WAFER CLEANING

✓ OUR SOLUTIONS REDUCE CARBON **CONCENTRATIONS FROM 55% TO** 0.1%

### PACKAGE CLEANING

- ✓ FLIP CHIPS
- ✓ CMOS *√*



**E-MOBILITY & HIGH VOLTAGE** CLEANING SOLUTIONS TO REMOVE FLUX RESIDUES







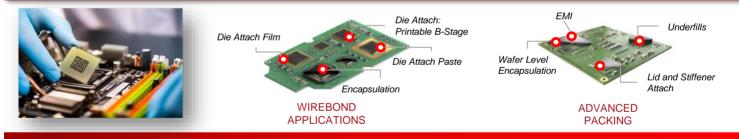
### GLOBAL INNOVATION LEADER OF ELECTRONIC ASSEMBLY MATERIALS



CONSUMER ELECTRONICS : ADHESIVE SOLUTIONS FOR CONSUMER ELECTRONICS



SEMICONDUCTOR PACKAGING : INNOVATIVE MATERIALS FOR EVOLUTIONARY ELECTRONICS CAPABILITY



**INDUSTRIAL & INFRASTRUCTURE :** POWER, AUTOMATING AND CONNECTING THE WORLD









LIGHTING



DATA & TELECOM INFRASTRUCTURE

SOLAR ENERGY : FACILITATING NEXT-GENERATION SOLAR TECHNOLOGIES WITH INNOVATIVE MATERIALS





POWER **GENERATION AND** CONVERSION



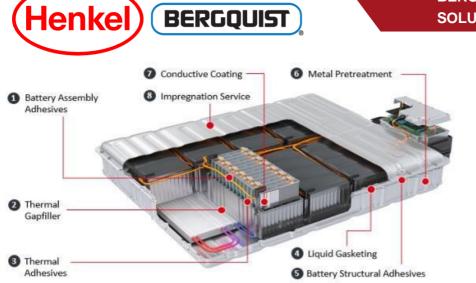
WIND ENERGY



ALTERNATIVE **ENERGY POWER** CONVERSION



Henkel





**BERGQUIST THERMAL MANAGEMENT** 





Thermal Materials

Thermal Substrates





Membrane Switches

Fans and Blowers



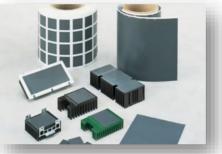
THERMAL GAP FILLERS THERMALLY CONDUCTIVE, LIQUID GAP FILLING MATERIALS



ADHESIVES HIGH STRUCTURAL IN SEVERE ENVIRONMENTS



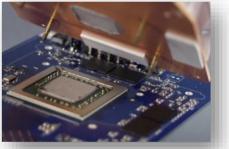
THERMAL GAP PADS DESIGNED TO FILL AIR GAPS AND ENHANCE THERMAL CONDUCTIVITY



PHASE CHANGE MATERIALS PRE-APPLIED, DRY MATERIAL WITH BETTER LONG-TERM THERMAL PERFORMANCE AND LESS MESS THAN GREASE



SIL PADS ELECTRICALLY AND NON-ELECTRICALLY INSULATING



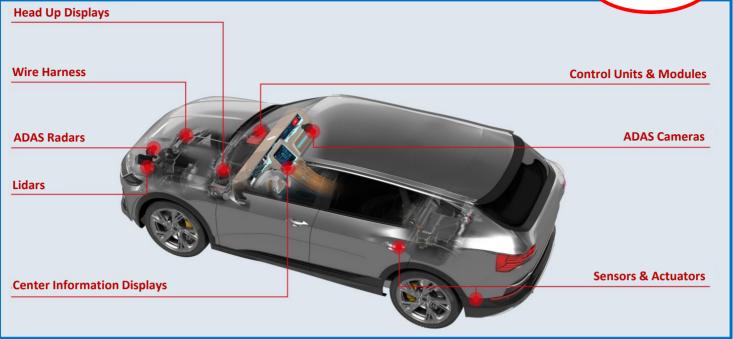
THERMALLY CONDUCTIVE GREASE ENSURING HIGH THERMAL TRANSFER ON AN INTERFACE,

# COMPREHENSIVE SOLUTIONS FOR AUTOMOTIVE ELECTRONIC COMPONENTS



### AUTOMOTIVE SOLUTION





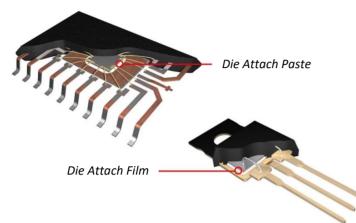




### **LEADFRAME SOLUTIONS**

### WIREBOND LEADFRAME SOLUTIONS :

Adhesive electronic solutions for leadframe, laminate and smart card



### WAFER LEVEL ENCAPSULATION

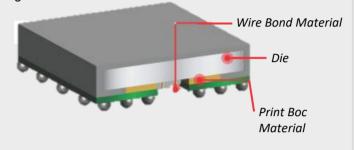
### **KEY BENEFITS OF HENKEL LCM**

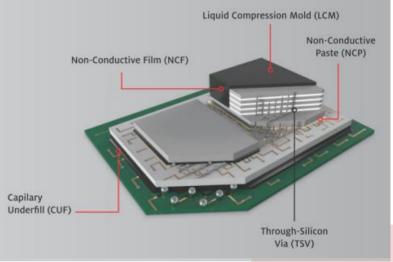
- · Low viscosity for easy flow and better fill
- · Better handling, no dust
- Ultra-low warpage, low CTE & low modulus for water handling & processing
- Low temperature and fast in-mold cure for increased UPH
- · EU REACH compliant anhydride-free

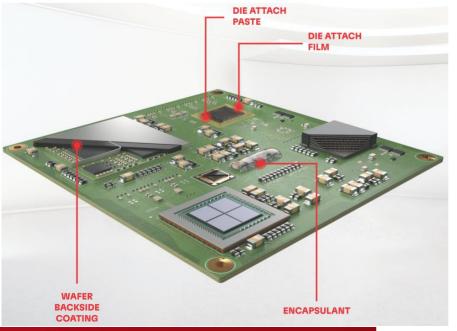
### PRINTABLE BOC DIE ATTACH MATERIALS

Board-on-Chip (BoC) is a common chip-scale packing technique for memory devices, particularly DRAM. Because of the requirement for controlled tolerances and fine features, die attach materials must deliver key attributes like minimized die tilt, uniform bond line thickness, and little to no fillet formation.

Henkel has perfected B-stage printable adhesives that align with mass production dynamics and enable fine feature designs.





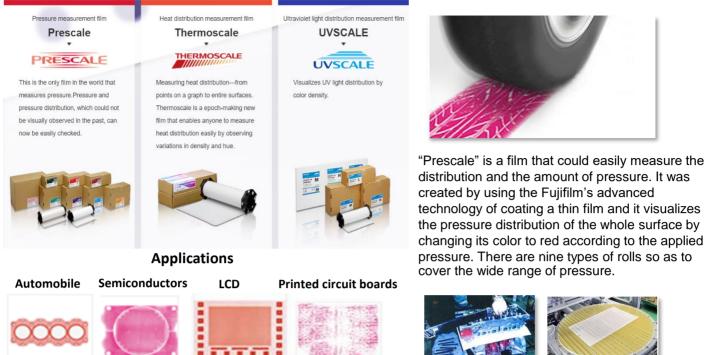


### LAMINATE PACKAGING MATERIALS

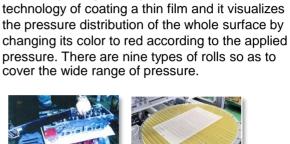
In addition to Henkel's well-known Bismaleimade (BMI)-based adhesives, new advances in IC packaging materials have been developed to facilitate high performance for various package designs – from LGAs to large format SiPs and SoMs. Products are available in paste, liquid, and film mediums, offering processing flexibility and precision for the most demanding applications and manufacturing environments.

### Easily measuring pressure, heat and UV light with film.

# **FUJ!FILM** Industrial



### Pleated Cartridge Filter / Capsule Filter





#### Absolute Type

- Polysulfone membrane
- Lineup of pore sizes from 0.03um~1.2um
- Lineup series
- PSE-W, PSF, PSK, PSS03, PSE05, PSE-L, PSE-XL, PSE-UXL/SXL



#### **Capsule filter**

- Polysulfone membrane
- Pore size of 0.1~0.45um
- Lineup series :
- **PSE** Capsule .



#### **Nominal Type**

- Polyproplyene membrane
- Lineup of pore sizes from 0.4um~30um
- Lineup series :
- PPE. PPE-UXL

### **SMT SPARE PARTS**

- **Panasonic** 
  - SIEMENS

### **HITACHI**

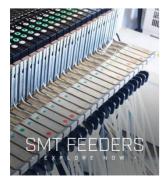
JUKI

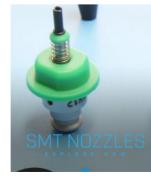


Assembleon



(UniversaL









SAMSUNG

Dek

### **V.L.K. WAREHOUSE & STORAGE SYSTEM**

- > AIR CONDITION CONTROL
- > 25°C (± 3°C)
- > OPEN AIR CONDITION 24 HOURS > ALARM SYSTEM
- HUMIDITY 40-70
- FIFO CONTROL
- FLAMABLE STORAGE ROOM
- BATTERY BACKUP
- > GENERATOR
- ALARM SYSTEM (VOICE/SMS ALARM)
- > TEMP DATA LOGGER : REAL TIME RECORD TEMP MONITORING.





LINE Notify  $\cap$ Freezer (VLK): Line Group 1 Name : R1 (-40°c) Status : TURNED TO NORMAL. NORMAL. Temperature : -44.7 °C Set (Max/Min) : -35.0/-45.0 °C Time : 14:29:15 21/05/2024. LINE Notify LINE Notify Freezer (VLK): Line Group 1 Name : R1 (-40°c) Status : TURNED TO NORMAL. POE LAN SWITCH NORMAL. Temperature : -44.7 °C Set (Max/Min) : -35.0/-45.0 °C Time : 16:10:14 21/05/2024. -----ADSL MODEM ---------UTP CABLE REMOTE PC Wifi UTP CABLE POE FREEZER MONITOR MODULE CLIENT PC ALARM SMS GSM MODEM SERVER

### **V.L.K. DIE-CUTTING**



### TOTAL SOLUTION IN THERMAL MANAGEMENT

- Available in custom sheets and die-cut shapes.
- V.L.K.. stocks and sources a variety of materials for die cut thermal gap pads.

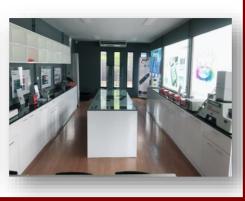


We offer customized solutions to meet our customers' needs.

We can make follow customer designed.

### V.L.K. TECHNICAL LAB







TECHNICAL LAB FOR TEST



FREE SUPPORT

**DOWNLOAD ADHESIVE** TO SERVE VARIOUS PACKAGE SIZE



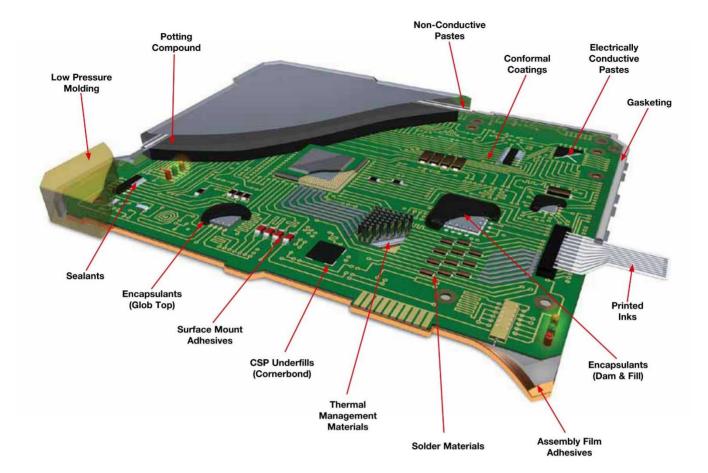








### NOTED

Line@



### 149049



Website



#### Address :

36/7 Moo 13, Bungkumploy Sub-District, Lam Luk Ka District, Pathumthani 12150

**Telephone No**. : +66 2-150-0247-51 Fax : +66 2-150-0252 Mobile :+66 81-430-1551

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